HOSTAFORM® XGC10 XAP®

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Hostaform® XGC10 XAP® is an acetal copolymer reinforced with approximately 10% glass fibers. Compared to the Hostaform® C 9021 GV 1/10, Hostaform® XGC10 XAP® has a higher strength and lower emissions.
Emissions according to VDA 275 < 10 ppm [mg/kg].

Product information

Resin Identification	POM-GF10	ISO 1043
Part Marking Code	>POM-GF10<	ISO 11469

Rheological properties

Melt volume-flow rate	3	cm^3/10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Moulding shrinkage, parallel	1.2	%	ISO 294-4, 2577
Moulding shrinkage, normal	1.1	%	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	4800	MPa	ISO 527-1/-2
Tensile stress at break, 5mm/min	110	MPa	ISO 527-1/-2
Tensile strain at break, 5mm/min	4.9	%	ISO 527-1/-2
Flexural modulus	4200	MPa	ISO 178
Charpy impact strength, 23°C	60	kJ/m^2	ISO 179/1eU
Charpy notched impact strength, 23°C	8.5	kJ/m^2	ISO 179/1eA
Charpy notched impact strength, -30°C	7	kJ/m^2	ISO 179/1eA
Poisson's ratio	0.36[C]		

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	154	°C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	60	E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	80	E-6/K	ISO 11359-1/-2

Flammability

Burning rate, Thickness 1 mm	66.3	mm/min	ISO 3795 (FMVSS 302)

Physical/Other properties

Density	1480	kg/m^3	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	200	°C
Min. melt temperature	190	°C

HOSTAFORM® XGC10 XAP®

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Max. melt temperature	210	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	100	°C
Min. mould temperature	80	°C
Max. mould temperature	120	°C
Hold pressure range	60 - 120	MPa
Back pressure	2	MPa
Ejection temperature	134	°C

Characteristics

Processing	Injection Moulding
Special characteristics	Low emissions

Additional information

Processing Notes

Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

Storage

The product can then be stored in standard conditions until processed.

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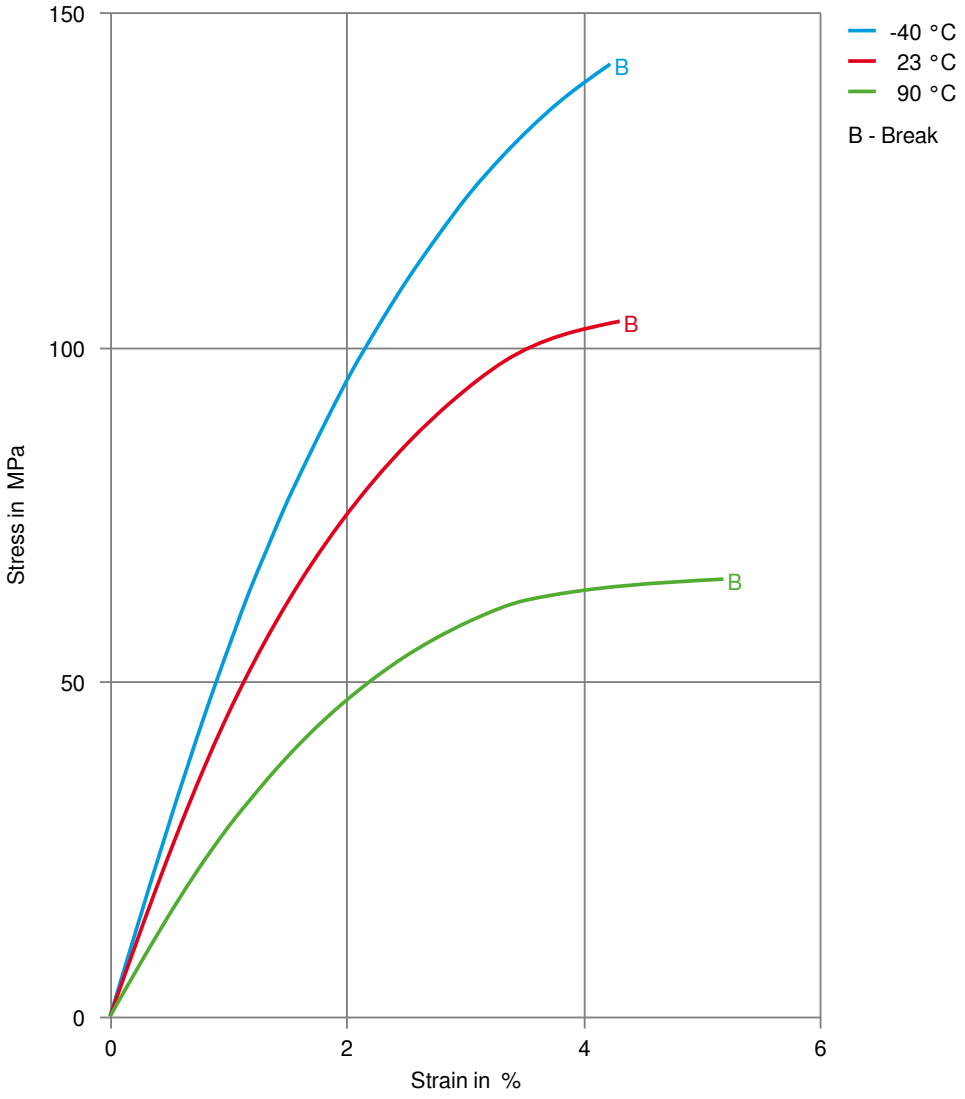
Stress-strain



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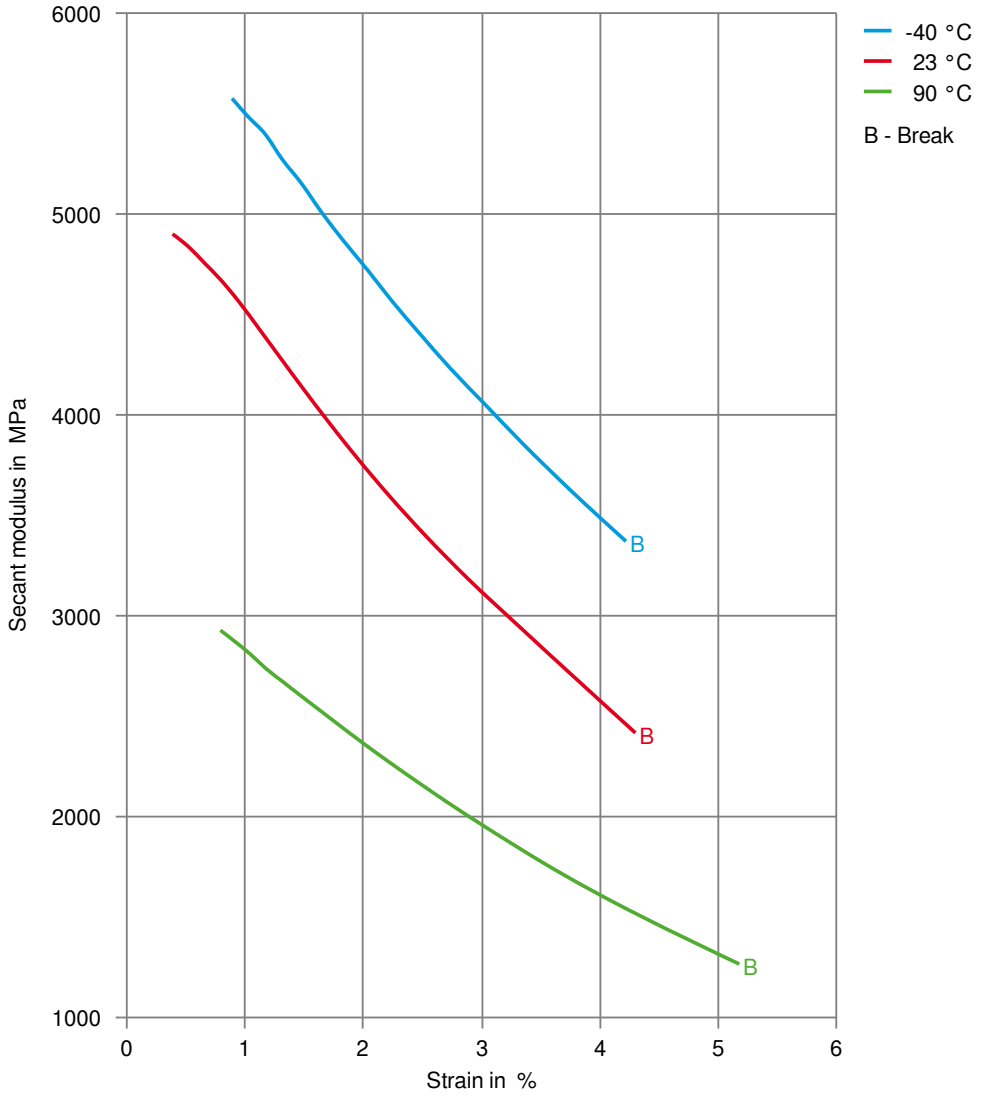
Secant modulus-strain



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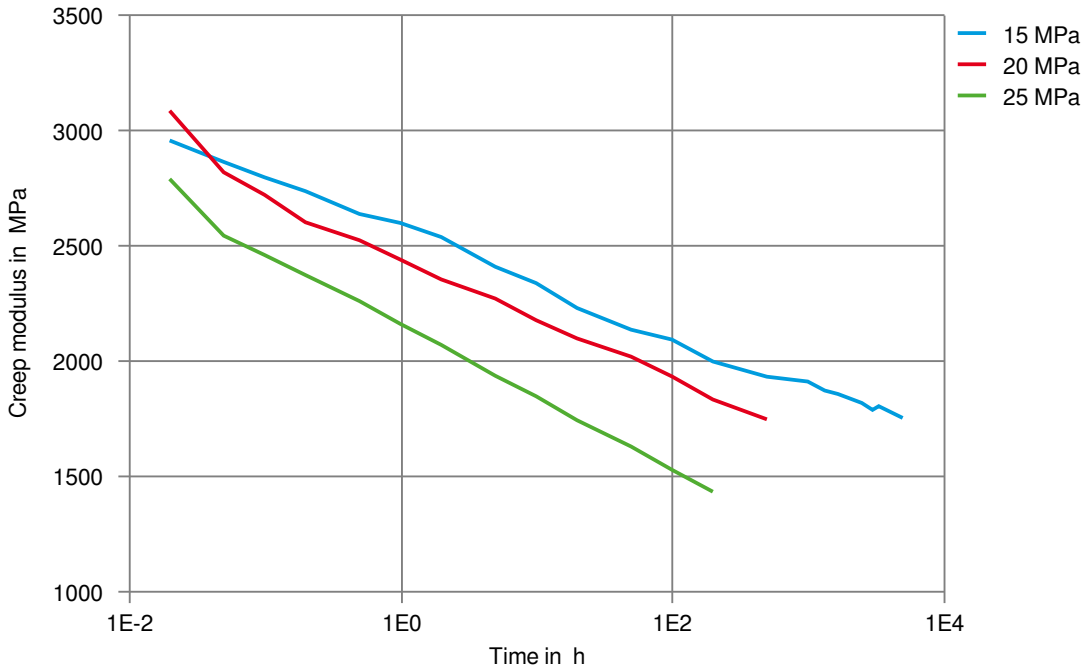
Creep modulus-time 90 °C



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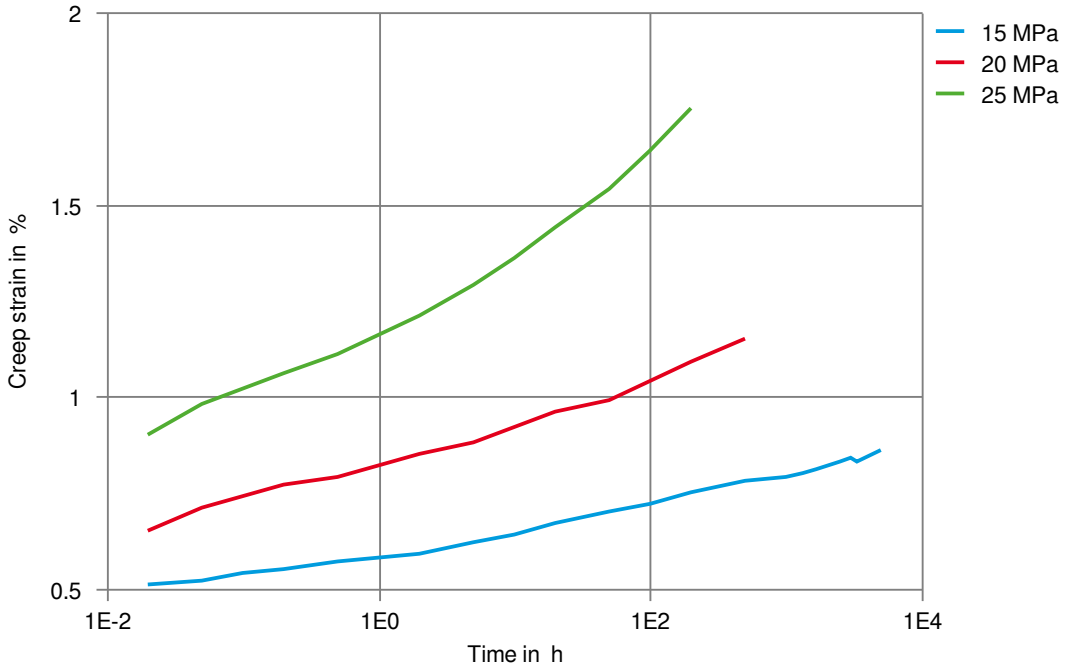
Creep strain-time 90 °C



Revised: 2024-07-12 Source: Celanese Materials Database